--- Special Section on Low-Power and High-Speed Chips and Systems ---

The IEICE (Institute of Electronics, Information and Communication Engineers) Transactions on Electronics announces a forthcoming special section on Low-Power and High-Speed Chips to be published in June 2025.

The objective of the special section is to discuss advancement of low-power and high-speed chips and leading-edge technologies in all areas of microprocessors and their applications. The special section solicits paper submission from anyone in this field. The authors working in this area are strongly encouraged to submit original research papers.

1. Scope

The major topics of interest include, but not limited to:


2. Submission Instructions

The deadline for submission is June 14, 2024 (Japan Standard Time). The standard number of pages is 8 for a PAPER. The maximum number of pages of a Brief Paper is 4. The article processing charge is considerably higher for extra pages. Manuscripts should be prepared according to the guideline in the "Information for Authors". The latest version is available at the web site, https://www.ieice.org/eng/shiori/mokuji_es.html. Note that the submitted manuscripts are required to cite 30 or more references for full paper and 15 or more references for brief paper, and that papers with fewer references will be rejected. The term for revising the manuscript after acknowledgement of conditional acceptance for this special section could be shorter than that for regular issues (60 days) because of the tight review schedule.

This special section will accept only papers by electronic submission. Prospective authors are requested to follow carefully the submission process described below.

Submit a paper using the IEICE web site, https://review.ieice.org/regist/regist_baseinfo_e.aspx. Authors should choose the [Special-LH] Low-Power and High-Speed Chips as a "Journal / Section" on the online screen. Do not choose [Regular-EC].

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